


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	MULTI-SUBSTRATE CIRCUIT ASSEMBLY		
Application Type : regular, utility			
Attorney Docket Number : DP-311231			
Correspondence address:			
Customer Number:		27127	
Inventors Information:			
<u>Inventor 1:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	US		
Name prefix:	Mr.		
Given Name:	Todd		
Middle Name:	P.		
Family Name:	Oman		
Residence:			
City of Residence:	Greentown		
State of Residence:	IN		
Country of Residence:	US		
Address-1 of Mailing Address:	7103 E. 50 North		
Address-2 of Mailing Address:			
City of Mailing Address:	Greentown		
State of Mailing Address:	IN		
Postal Code of Mailing Address:	46936		
Country of Mailing Address:	US		
Phone:			
Fax:			
E-mail:			
<u>Inventor 2:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	US		
Name prefix:	Mr.		

Given Name: Thomas
Middle Name: A.
Family Name: Degenkolb
Residence:
City of Residence: Noblesville
State of Residence: IN
Country of Residence: US
Address-1 of Mailing Address: 1606 Chestnut Court
Address-2 of Mailing Address:
City of Mailing Address: Noblesville
State of Mailing Address: IN
Postal Code of Mailing Address: 46060
Country of Mailing Address: US
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

27127



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Assignee 1:

Organization Name: Delphi Technologies, Inc.
Address-1 of Mailing Address: P. O. Box 9005
Address-2 of Mailing Address: One Corporate Center CT10C
City of Mailing Address: Kokomo
State of Mailing Address: IN
Postal Code of Mailing Address: 46904-9005
Country of Mailing Address: US
Phone:
Fax:
E-mail: